

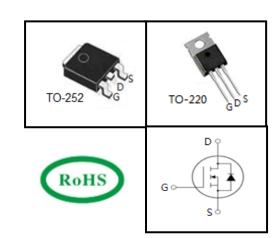
40V N-Channel Trench MOSFET

FEATURES

- Trench Power MOSFET Technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized For Fast-switching Applications

APPLICATIONS

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial



Device Marking and Package Information			
Device	Package	Marking	
TTD120N04AT	TO-252	120N04AT	
TTP120N04AT	TO-220	120N04AT	

Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{GS} = 0V)	$V_{\rm DSS}$	40	V
Continuous Drain Current	I _D	120	А
Pulsed Drain Current (note1)	I _{DM}	480	А
Gate-Source Voltage	V_{GSS}	±20	V
Single Pulse Avalanche Energy (note2)	E _{AS}	138.4	mJ
Avalanche Current	I _{As}	35	А
Power Dissipation (T _C = 25°C)	P_{D}	143	W
Operating Junction and Storage Temperature Range	T_J,T_stg	-55~+175	°C

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R _{thJC}	1.05	IZ 0.07
Thermal Resistance, Junction-to-Ambient	R _{thJA}	60	K/W

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Parameter	Symbol	To at Oan distance	Value			
		Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_{D} = 250\mu A$	40			V
7 0 1 1/1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		$V_{DS} = 40V, V_{GS} = 0V, T_{J} = 25^{\circ}C$	-		1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 40V, V_{GS} = 0V, T_{J} = 150^{\circ}C$	-		100	
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20V$			±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0	1.7	2.4	V
Dunin Course On Benistance (Nets2)	Б	$V_{GS} = 10V, I_{D} = 30A$		2.7	3.5	mΩ
Drain-Source On-Resistance (Note3)	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 30A$		3.6	4.7	mΩ
Forward Transconductance (Note3)	g _{fs}	V _{DS} = 10V, I _D =20A		45.5		S
Dynamic						
Input Capacitance	C _{iss}	V - 0V		10179		
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 20V,$		587		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		439		
Total Gate Charge	Q_g			132		
Gate-Source Charge	Q_gs	$V_{DD} = 20V, I_{D} = 20A,$ $V_{GS} = 10V$		23		nC
Gate-Drain Charge	Q_{gd}	GS -		23		1
Turn-on Delay Time	t _{d(on)}			27		
Turn-on Rise Time	t _r	$V_{DD} = 20V, I_{D} = 20A,$		11		
Turn-off Delay Time	t _{d(off)}	$R_G = 3\Omega$		83		ns
Turn-off Fall Time	t _f			14		
Drain-Source Body Diode Characteris	stics					
Continuous Body Diode Current	I _S	T _C = 25°C			120	Δ.
Pulsed Diode Forward Current	I _{SM}				480	Α
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 20A$, $V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t _{rr}	$I_F = 20A$, $di_F/dt = 100A/\mu s$		66		ns
Reverse Recovery Charge	Q _{rr}			73		nC

Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. V_{DD} = 40V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}C$
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1%



Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

Figure 4 Output Characteristics

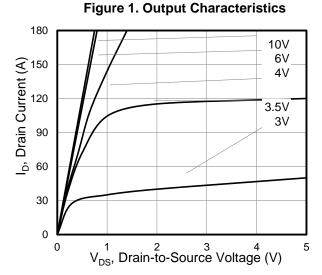


Figure 3. On-Resistance vs. Drain Current

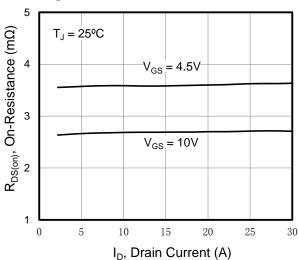


Figure 5. Gate Charge

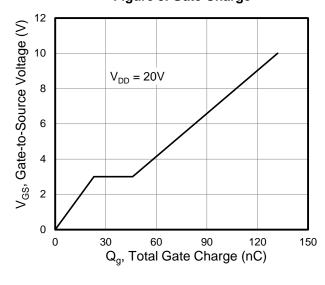


Figure 2. Transfer Characteristics

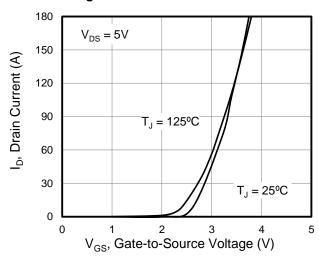


Figure 4. Capacitance

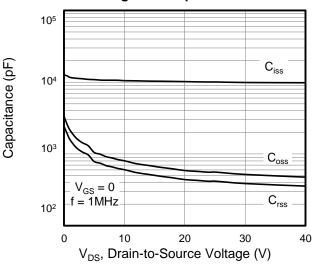
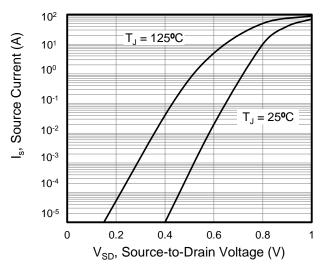


Figure 6. Body Diode Forward Voltage





Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 7. On-Resistance vs.

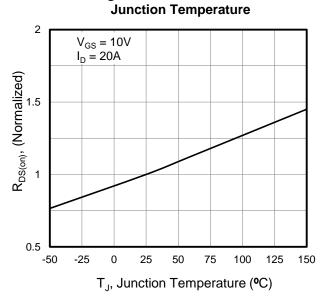


Figure 8. Threshold Voltage vs. Junction Temperature

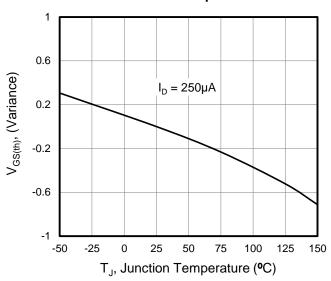


Figure 9. Transient Thermal Impedance

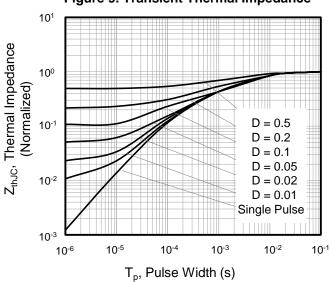




Figure A: Gate Charge Test Circuit and Waveform

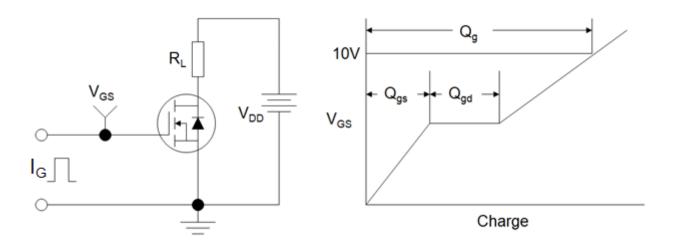


Figure B: Resistive Switching Test Circuit and Waveform

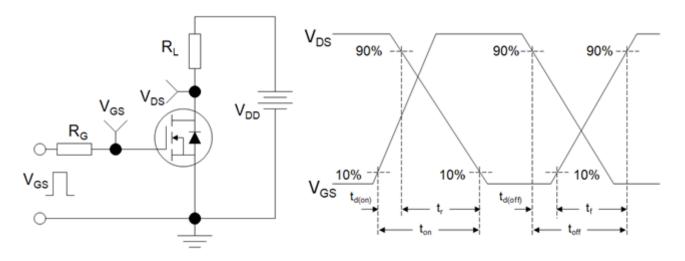
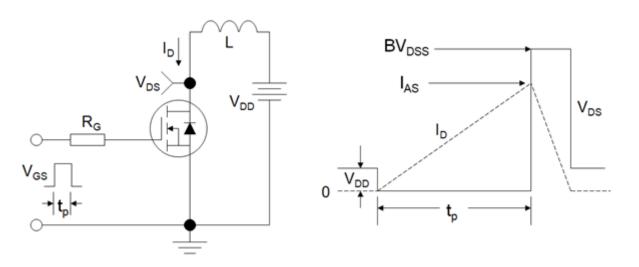
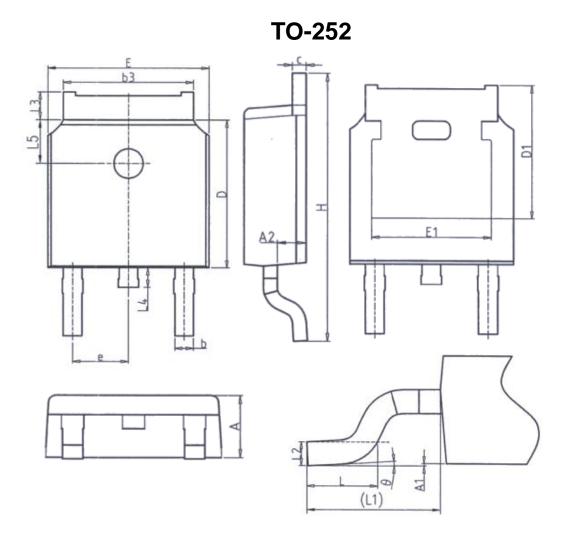


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



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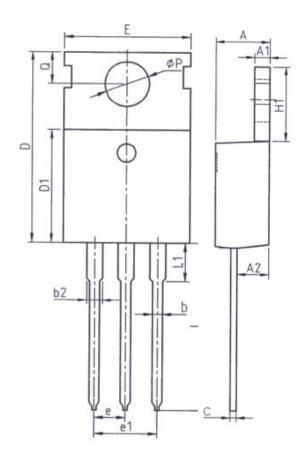


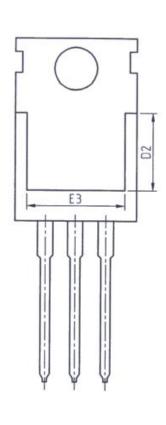


Unit: mm			
Symbol	Min.	Max.	
Α	2. 20	2. 40	
A1	0.00	0. 20	
A2	0. 97	1. 17	
b	0. 68	0.90	
b3	5. 20	5. 50	
С	0. 43	0. 63	
D	5. 98	6. 22	
D1	5. 30REF		
E	6. 40	6. 80	
E1	4. 63	_	

Unit: mm			
Symbol	Min.	Max.	
е	2. 28	6BSC	
Н	9. 40	10.50	
L	1. 38	1. 75	
L1	2. 90REF		
L2	0. 51BSC		
L3	0.88	1. 28	
L4	_	1.00	
L5	1. 65	1. 95	
θ	0°	8°	

TO-220





Unit: mm		
Symbol	Min.	Max.
Α	4. 37	4. 77
A1	1. 25	1. 45
A2	2. 20	2. 60
ь	0. 70	0. 95
b2	1. 17	1. 47
С	0. 40	0. 65
D	15. 10	16. 10
D1	8. 80	9. 40
D2	5. 50	_

Unit: mm			
Symbol	Min.	Max.	
E	9. 70	10. 30	
E3	7. 00	-	
е	2. 54BSC		
e1	5. 08BSC		
H1	6. 25	6. 85	
L	12. 75	13.80	
L1	-	3. 40	
P	3. 40	3. 80	
Q	2. 60	3. 00	



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